

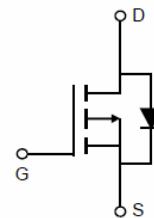
### P-Channel Enhancement Mode Power MOSFET

#### Description

The MSP3040D uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge .This device is well suited for use as a load switch or in PWM applications.

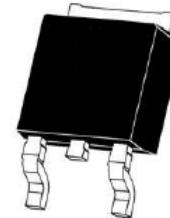
#### General Features

- $V_{DS} = -40V, I_D = -30A$
- $R_{DS(ON)} < 35m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} < 45m\Omega @ V_{GS} = -4.5V$
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation



Schematic diagram

MARKING:30P04



TO-252 -2Ltop view

#### Application

- Load switch
- PWM application

#### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-30	A
Pulsed Drain Current	$I_{DM}$	-60	A
Maximum Power Dissipation	$P_D$	50	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ C$

#### Thermal Characteristic

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	3.0	$^\circ C/W$
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### Electrical Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise noted)

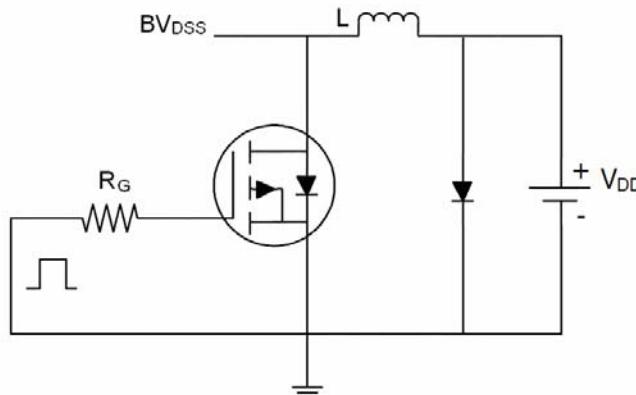
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{DSS}$	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-40	-	-	V
Zero Gate Voltage Drain Current	$I_{DS}$	$V_{DS}=-40\text{V}, V_{GS}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm20\text{V}, V_{DS}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.0	-1.5	-2.0	V
Drain-Source On-State Resistance	$R_{DS(\text{ON})}$	$V_{GS}=-10\text{V}, I_D=-15\text{A}$	-	29	35	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-10\text{A}$	-	34	45	$\text{m}\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-5\text{V}, I_D=-15\text{A}$	-	10	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{iss}$	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}, F=1.0\text{MHz}$	-	930	-	PF
Output Capacitance	$C_{oss}$		-	85	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	35	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-20\text{V}, R_L=1\Omega, V_{GS}=-10\text{V}, R_G=3\Omega$	-	8	-	nS
Turn-on Rise Time	$t_r$		-	4	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	32	-	nS
Turn-Off Fall Time	$t_f$		-	7	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-20, I_D=-15\text{A}, V_{GS}=-10\text{V}$	-	25	-	nC
Gate-Source Charge	$Q_{gs}$		-	3	-	nC
Gate-Drain Charge	$Q_{gd}$		-	7	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0\text{V}, I_S=-15\text{A}$	-		-1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_S$		-	-	-15	A
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}, I_F = -15\text{A}$ $dI/dt = -100\text{A}/\mu\text{s}$ <sup>(Note 3)</sup>	-	25		nS
Reverse Recovery Charge	$Q_{rr}$		-	31		nC

### Notes:

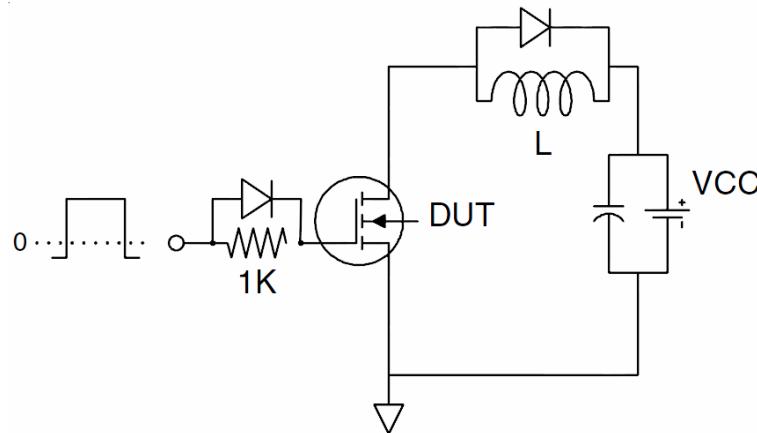
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

### Test Circuit

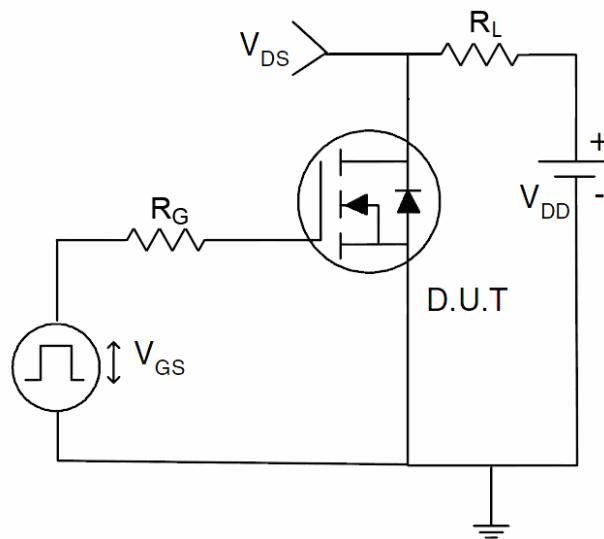
#### 1) E<sub>AS</sub> test Circuit



#### 2) Gate charge test Circuit



#### 3) Switch Time Test Circuit



### P- Channel Typical Electrical and Thermal Characteristics (Curves)

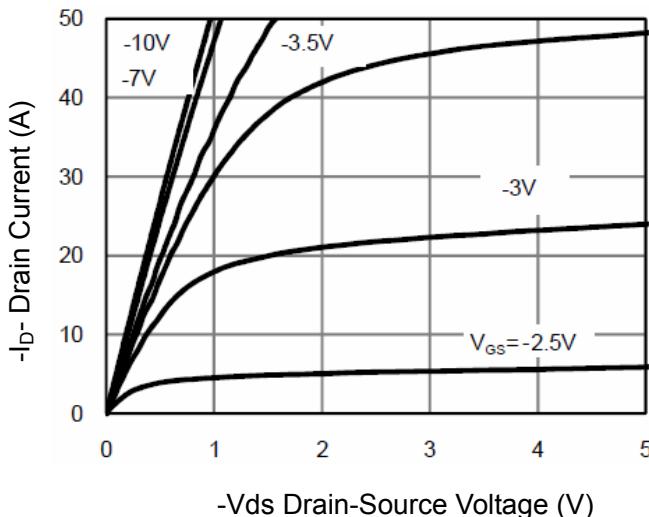


Figure 1 Output Characteristics

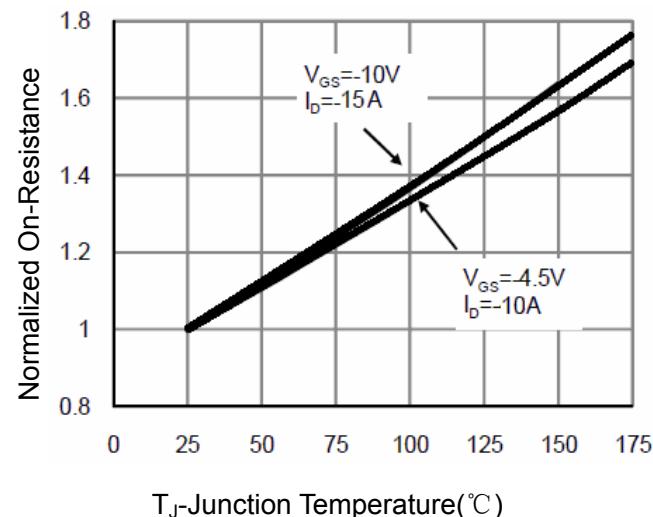


Figure 4  $R_{DS(on)}$ -Junction Temperature

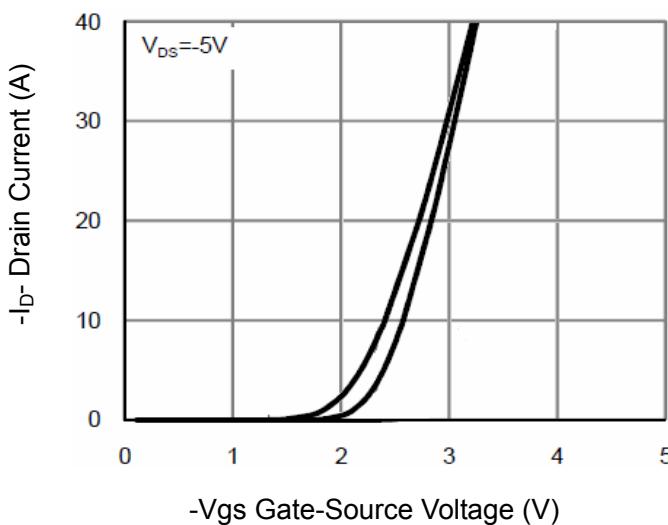


Figure 2 Transfer Characteristics

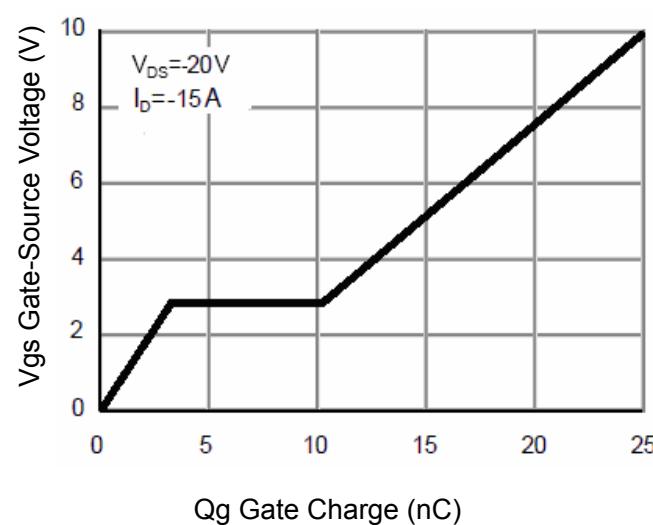


Figure 5 Gate Charge

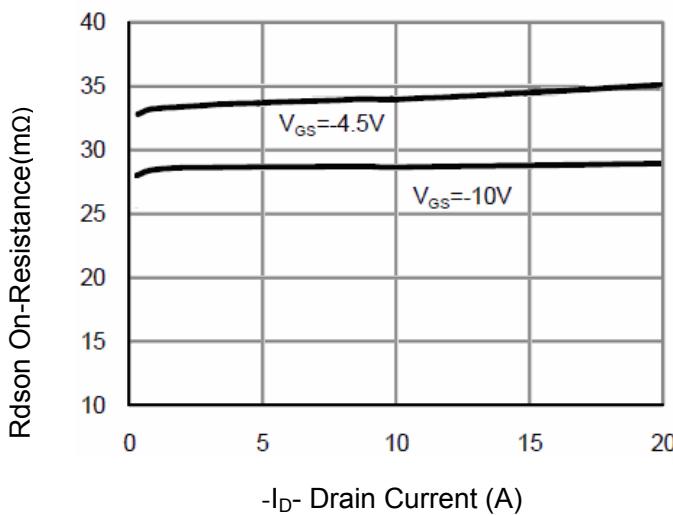


Figure 3  $R_{DS(on)}$ - Drain Current

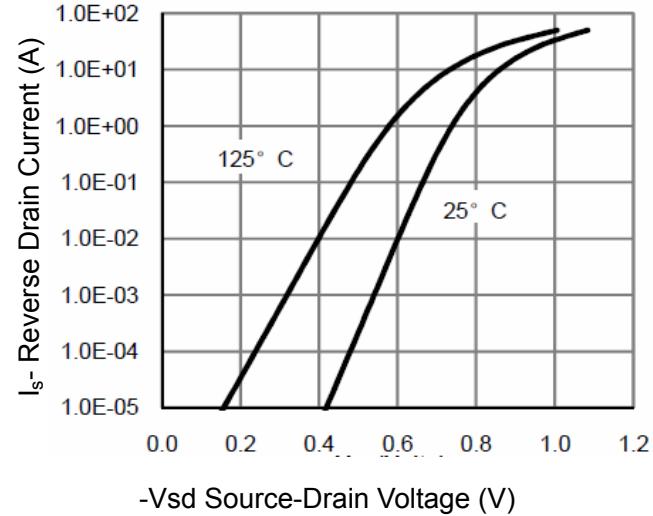
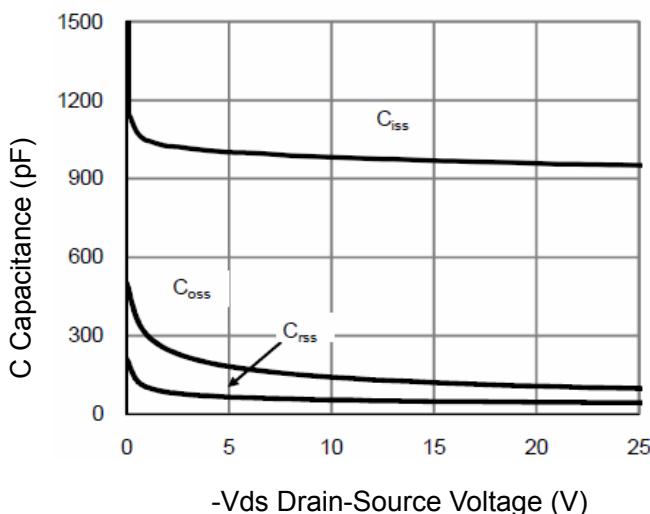
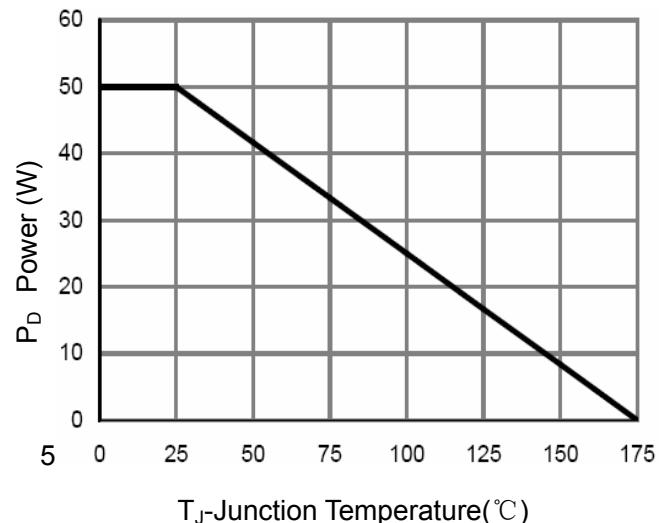


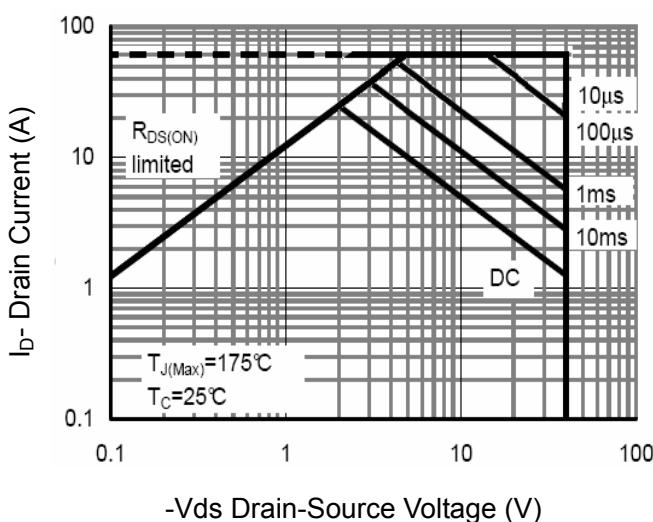
Figure 6 Source- Drain Diode Forward



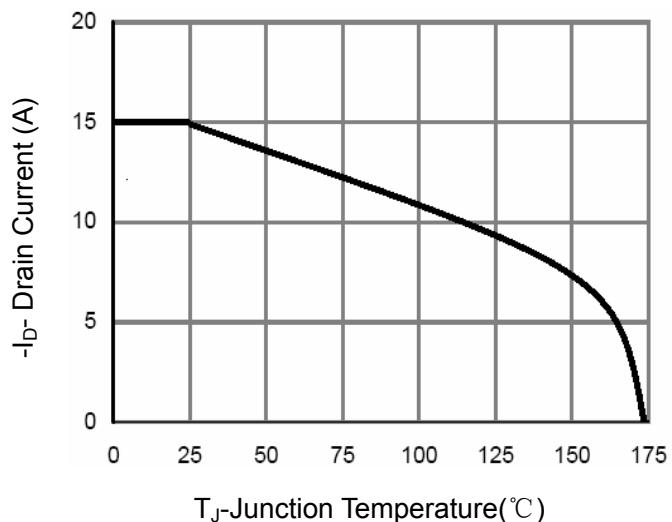
**Figure 7 Capacitance vs Vds**



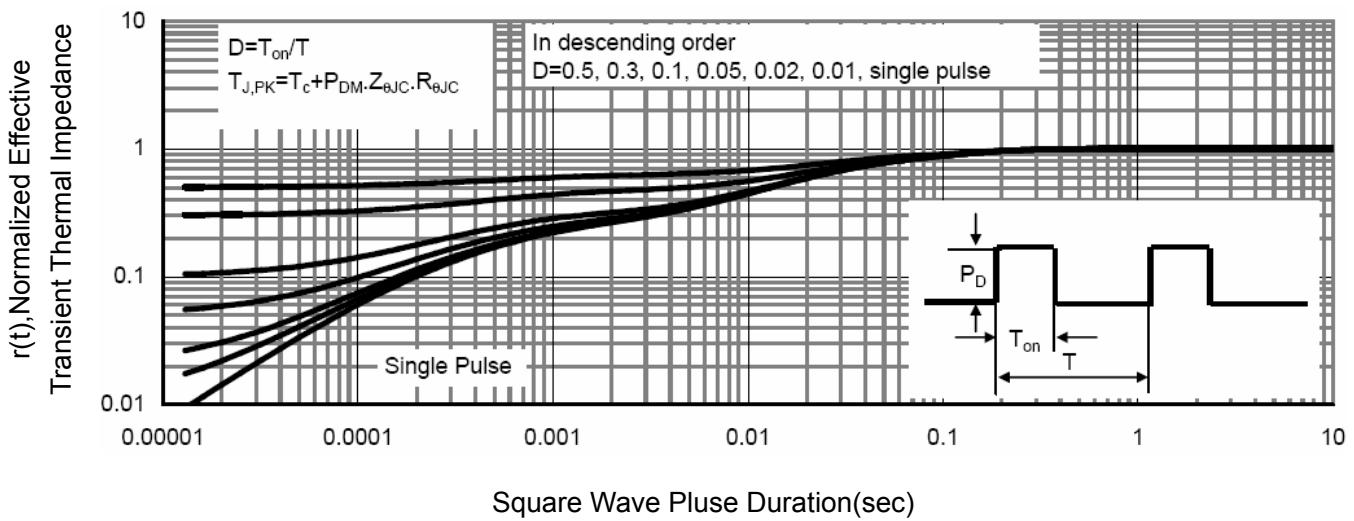
**Figure 9 Power Dissipation**



**Figure 8 Safe Operation Area**

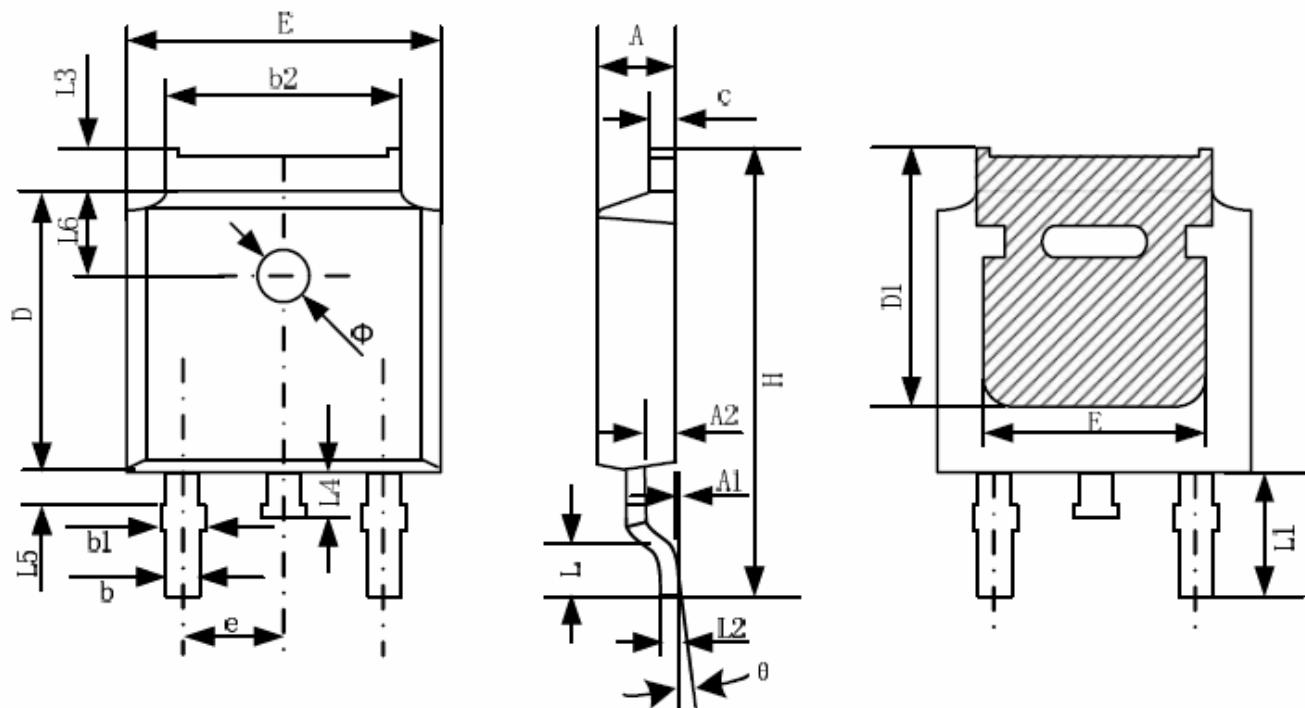


**Figure 10 ID Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

### TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.38	0.087	0.094
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.043
b	0.72	0.85	0.028	0.033
b1	0.72	0.90	0.028	0.035
b2	5.13	5.46	0.202	0.215
c	0.47	0.60	0.019	0.024
D	6.00	6.20	0.236	0.244
D1	5.25	--	0.207	--
E	6.50	6.70	0.256	0.264
E1	4.70	--	0.185	--
e	2.19	2.39	0.086	0.094
H	9.80	10.40	0.386	0.409
L	1.40	1.70	0.055	0.067
L1	2.90 REF		0.114 REF	
L2	0.508 BSC		0.020 BSC	
L3	0.90	1.25	0.035	0.049
L4	0.60	1.00	0.024	0.039
L5	0.15	0.75	0.006	0.030
L6	1.80 REF		0.071 REF	
Φ	1.20	1.40	0.047	0.055
θ	0°	8°	0°	8°